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# Specification for Approval

Customer:	
Model Name:	

Sı	Customer approval		
R&D Designed	R&D Approved	QC Approved	
Peter	Peng Jun		



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# **Revision Record**

REV NO.	REV DATE	CONTENTS	Note
Α	2013-07-16	NEW ISSUE	

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### 1. Scope

This specification defines general provisions as well as inspection standards for TFT module supplied by AMSON electronics.

If the event of unforeseen problem or unspecified items may occur, naturally shall negotiate and agree to solution.

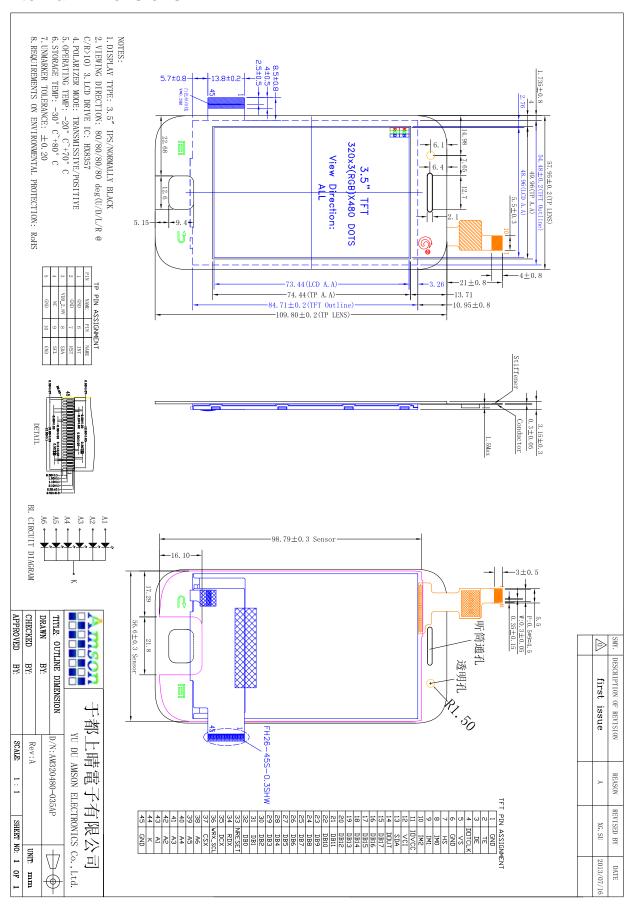
### 2. General Information

ITEM	STANDARD VALUES	UNITS
LCD type	3.5"TFT	
Dot arrangement	320(RGB)×480	dots
Color filter array	RGB vertical stripe	
Display mode	IPS / Transmission / Normally Black	
Viewing Direction	80/80/80/80 deg(U/D/L/R @ C/R>10)	
Driver IC	HX8357	
Module size	57.95(W)×109.80(H)×3.15(T)	mm
Active area	48.96(W)×73.44(H)	mm
Dot pitch	0.153(W)×0.153(H)	mm
Interface	4-lines_8bit / 3-lines_9bit SPI 8-/ 9-/16-/18-bit 8080-series system interface 16-/18-bit RGB interface	
Operating temperature	-20 ~ +70	°C
Storage temperature	-30 ~ +80	°C
Back Light	6 White LED	
Weight	TBD	g

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#### 3. External Dimensions





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## 4. Interface Description

## 4.1 TFT interface

Pin	Symbol	Description.								
1	GND	Power ground								
2	TE	Tearing effect output pin to synchronize MCU to frame writing.								
3	DE	Data enable signal in RGB I/F mode								
4	DOTCLK	Pixel clock signal in RGB I/F.								
5	VS	Vertical sync signal in RGB I/F.								
6	GND	Power ground								
7	HS	Horizontal sync signal in RGB I/F.								
	11.40	System interface Mode								
8	IM0	IM2 IM1 IM0 interface mode DB Pin								
		0 0 0 8080 18-bit interface DB[17:0]								
9	IM1	0 0 1 8080 9-bit interface DB[8:0]								
	1141 1	0 1 0 8080 16-bit interface DB[15:0]								
		0 1 1 8080 8-bit interface DB[7:0]								
10	IM2	1         0         1         3-wire_9-bit SPI         CSX,SDA,SCL           1         1         1         4-wire_8-bit SPI         CSX,DCX,SDA,SCL								
		1 1 1 4-wire_8-bit SPI CSX,DCX,SDA,SCL								
11	IOVCC	A supply voltage to the logic circuit.								
12	VCI	A supply voltage to the analog circuit.								
13	SDA	Serial input signal in SPI I/F.								
14	DOUT	Serial output signal in SPI I/F.								
15	DB17									
16	DB16									
17	DB15									
18	DB14									
19	DB13									
20	DB12	18-bit parallel bi-directional data bus for MPU system:								
21	DB11	8-bit I/F: DB [7:0] is used. 9-bit I/F: DB [8:0] is used.								
22	DB10	9-bit i/F. DB [6.0] is used. 16-bit i/F: DB [15:0] is used.								
23	DB9	24-bit I/F: DB [17:0] is used.								
24	DB8	40 kiling Adalah a Garbor VII								
25	DB7	18-bit input data bus for RGB I/F. 16-bit/pixel: DB[17:13]=R[4:0], DB[11:6]=G[5:0] and DB[5:1]=B[4:0];								
26	DB6	16-bit/pixel: DB[17:13]=R[4:0], DB[11:6]=G[5:0] and DB[5:1]=B[4:0], 18-bit/pixel: DB[17:12]=R[5:0], DB[11:6]=G[5:0] and DB[5:0]=B[5:0];								
27	DB5	Connect unused pins to GND.								
28	DB4									
29	DB3									
30	DB2									
31	DB1									
32	DB0									



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33	NRESET	Reset input pin, Active "L".
34	RDX	Reads strobe signal to write data when RD is "Low" in MPU interface.
35	DCX	Display data / command selection in 80-series MPU I/F. DCX = "0" : Command DCX = "1" : Display data.
36	WRX_SCL	Writes strobe signal to write data when WRX is "Low" in MPU I/F. A synchronous clock signal in SPI I/F.
37	CSX	Chip select input pin ("Low" enable) in MPU I/F and SPI I/F.
38	A6	LED backlight (Anode).
39	A5	LED backlight (Anode).
40	A4	LED backlight (Anode).
41	A3	LED backlight (Anode).
42	A2	LED backlight (Anode).
43	A1	LED backlight (Anode).
44	K	LED backlight (Cathode).
45	GND	Power ground.

### **4.2 CTP interface**

Pin	Symbol	Description.
1	GND	Power ground.
2	GND	Power ground.
3	VDD_2.8V	Supply voltage.
4	NC	No Connection.
5	GND	Power ground.
6	INT	External interrupt INT to the host, it is active low when finger touching on the Screen.
7	RST	Reset.
8	SDA	I2C Serial Clock.
9	SCL	I2C Serial Data.
10	GND	Power ground.

5. Absolute Maximum Ratings

Item	Symbol	Min.	Max.	Unit
Logic Supply Voltage	IOVCC	-0.3	4.6	V
Analog Supply Voltage	VCI	-0.3	4.6	V
Input Voltage	Vin -0.3 IOVCC+0.3		V	
Operating Temperature	Тор	-20	70	°C
Storage Temperature	Тѕт	-30	80	°C
Storage Humidity	HD	20	90	%RH

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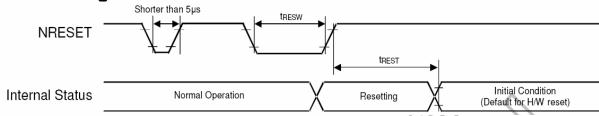
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### 6. DC Characteristics

Item	Symbol	Min.	Тур.	Max.	Unit	Remark
Logic Supply Voltage	IOVCC	1.65	1.8/2.8	3.3	٧	-
Analog Supply Voltage	VCI	2.5	2.8	3.3	٧	-
Input High Voltage	V <sub>IH</sub>	0.7IOVCC	-	IOVCC	V	Digital input pins
Input Low Voltage	V <sub>IL</sub>	-0.3	-	0.3IOVCC	٧	Digital input pins
Output High Voltage	V <sub>OH</sub>	0.8IOVCC	-	IOVCC	٧	Digital output pins
Output Low Voltage	V <sub>OL</sub>	0	-	0.2IOVCC	V	Digital output pins
I/O Leak Current	ILI	-1.0	-	1.0	$\mu$ A	-

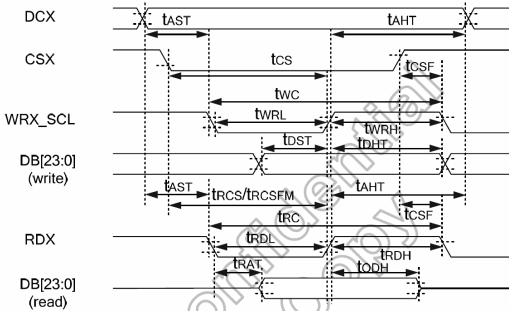
## 7. Timing Characteristics

## 7.1 Reset Timing Characteristics



Symbol	Darameter	Parameter Related Spec.		Note	Unit		
Syllibol	Faranietei	Pins	Min.	Тур.	Max.	Note	Oilit
tRESW	Reset low pulse width <sup>(1)</sup>	NRESET	10	-	- {//	-	μs
tREST Reset comple	Poset complete time (2)	-	5	~(	93)	When reset applied during SLPIN mode	ms
	neset complete tillle	-	120	(0)	)-	When reset applied during SLPOUT mode	ms

# 7.2 i80-System Interface Timing Characteristics



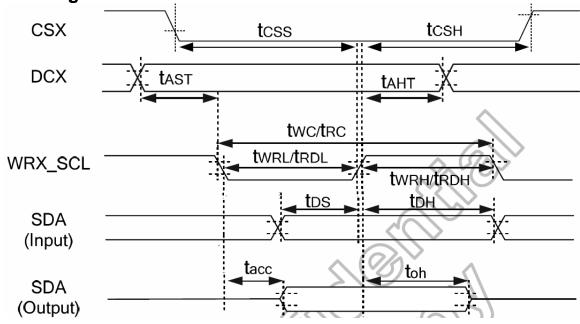


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Signal	Symbol	Parameter	Min.	Max.	Unit
DCV	<b>t</b> ast	Address setup time	0	-	
DCX	<b>t</b> aht	Address hold time (Write/Read)	10	-	ns
	tcs	Chip select setup time (Write)	10	-	
CSX	trcs	Chip select setup time (Read register)	45	-	ns
USA	trcsғм	Chip select setup time (GRAM)	355	-	115
	tcsf	Chip select wait time (Write/Read)	10	-	
	twc	Write cycle (write register)	50	-	
	twc	Write cycle (write GRAM@SLPOUT)	47	-	
WRX_SCL	twc	Write cycle (write GRAM@SLPIN)	100	-	ns
	twr	Control pulse "H" duration	15	-	
	twrl	Control pulse "L" duration	15	-	
	trc	Read cycle (read register)	160	-	
	trc	Read cycle (GRAM)	450	-	
RDX	tпрн	Control pulse "H" duration	90	-	ns
	trdl	Control pulse "L" duration(read register)	35	-	
	<b>t</b> RDL	Control pulse "L" duration(GRAM)	345	-	
	tost	Data setup time	10	-	
	<b>t</b> dht	Data hold time	10	-	
DB[23:0]	<b>t</b> rat	Read access time(read register)	-	40	ns
	<b>t</b> rat	Read access time(GRAM)	-	340	
	tорн	Output disable time	20	80	

7.3 SPI Timing Characteristics

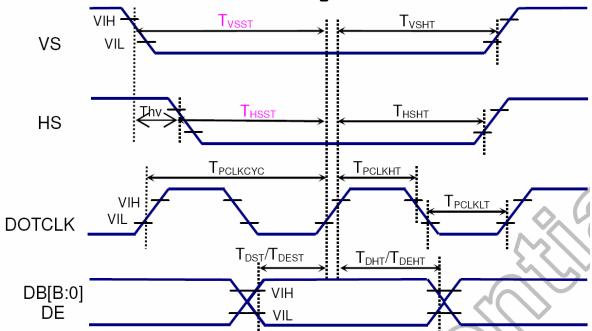


Signal	Symbol	Parameter	Min.	Max.	Unit	Description
	tcss	Chip select setup time (Write)	15	-		
CSX	tcss	Chip select setup time (Read)	60	-	ns	
03/	tсsн	Chip select hold time (Write)	15	-	115	<u> </u>
	tсsн	Chip select hold time (Read)	65	-		
DCX	tast	Address setup time	0	-	no	
DCX	taht	Address hold time (Write/Read)	10	-	ns	_
WRX SCL	twc	Write cycle	66	-		
(Write)	twr	Control pulse "H" duration	15	-	ns	-
(write)	twrL	Control pulse "L" duration	15	-		
WRX SCL	trc	Read cycle	150	-		
(Read)	trdh	Control pulse "H" duration	60	-	ns	-
(neau)	trdl	Control pulse "L" duration	60	-		
SDA 🔷	tos	Data setup time	10	-	nc	
(Input)	tон	Data hold time	10	-	ns	For maximum CL=30pF
SDA	tacc	Read access time	10	50	no	For minimum C <sub>L</sub> =8pF
(Output)	tон	Output disable time	15	50	ns	

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## 7.4 Parallel 18/16-bit RGB Interface Timing Characteristics

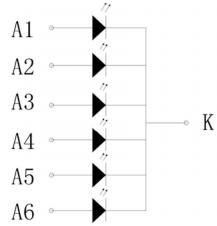


Item	Symbol	Symbol Condition		Spec.			
Item	Syllibol	Condition	Min.	Тур.	Max.	Unit	
Pixel low pulse width	$T_{CLKLT}$	(3//0	15	J)- V	-	ns	
Pixel high pulse width	T <sub>CLKHT</sub>	\\\\	15	7	-	ns	
Vertical Sync. set-up time	$T_{VSST}$		15	<del>-</del>	-	ns	
Vertical Sync. hold time	$T_{VSHT}$		<del>1</del> 5	-	-	ns	
Horizontal Sync. set-up time	T <sub>HSST</sub>	$\bigcirc$	15	-	-	ns	
Horizontal Sync. hold time	THSHT		15	-	-	ns	
Data Enable set-up time	$T_{DEST}$	2	15	-	-	ns	
Data Enable hold time	T <sub>DEHT</sub>		15	-	-	ns	
Data set-up time	T <sub>DST</sub>		15	-	-	ns	
Data hold time	T <sub>DHT</sub>	$\wedge$ (O)	15	-	-	ns	
Phase difference of sync signal falling edge	Thv		0	-	320	Dotclk	

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## 8. Backlight Characteristics



BL CIRCUIT DIAGRAM

Item	Symbol	MIN	TYP	MAX	UNIT	Test Condition
Supply Voltage	Vf	3.0	3.3	3.5	V	If=90mA
Supply Current	If		90	120	mA	
Luminous Intensity for LCM		200	240		Cd/m <sup>2</sup>	If=90mA
Uniformity for LCM		80			%	If=90mA
Life Time		50000			Hr	If=90mA
Backlight Color	t Color White					



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# 9. Capacitive Touch Panel 9.1 Features

Item	Description
TP Structure	PMMA /Glass
Sensor Structure	single side ITO
Controller IC	FT6206
Sensing	Mutual
Touch Points	Max 2 Points
Interface Type	I2C
Connector (with Host)	ZIF
TP OD (with Cover)	109.8*57.95mm
TP AA	74.44*49.96mm
TP VA	74.44*49.96mm (3.5inch)
Channel	11*2
Touch key	In Sensor AA
Touch key controller IC	NC

### 9.2 Mechanical

Item	Description	Note		
Operate	Finger			
Linearity	<5%			
Surface hardness (H)	≥6H	500g		
FPC Peeling	500g	Peeling direction: 90°; Velocity: 50mm/min.		
FPC Bending	After the test meet the electrical properties	Angle:180°; Radius: R1.0mm; 10times.		

### 9.3 Electrical

Item	Description	Note
Power supply voltage	2.8V	
I/O supply voltage	2.8V	
Current consumption (Normal mode)	6.36mA	
Current consumption (Green mode)	3.8mA	
Current consumption (Sleep mode)	100uA	
Supply noise	≦50mV	



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### 10. Optical Characteristics

Optical characteristics are determined after the unit has been 'ON' and stable for approximately 30 minutes in a dark environment at 25 °C. The values specified are at an approximate distance 50cm from the TFT-LCD surface at a viewing angle of  $\Phi$  and  $\theta$  equal to 0°. Measurement condition: Refer to next pages (LED back light with 20 mA/1 ea)

\*1): with LGD Polarizer;

\*2): Only Color Filter glass

j. Offig Color i liter glass						
Parameter	Cymhol	Values		Unit	Notos	
Parameter	Symbol	Min	Тур	Max	Offic	Notes
*1) Thursdayld Malke wa	Vsat	4.0	4.1	4.2	V	F: 2
*1) Threshold Voltage	Vth	1.9	2.0	2.1	V	Fig.2
*1) Transmittance	T(%)		4.4	-	%	Fig.1
*1) Contrast Ratio	C/R	-	500	-		
*1) Response Time	Tr+Tf	-	35	45	msec	Fig.3, Fig.5
	Rx	0.637	0.657	0.677		
	Ry	0.300	0.320	0.340		
	Gx	0.269	0.289	0.309		
*2) CIE Color Coordinate	Gy	0.569	0.589	0.609		
of CIE Color Coordinate	Bx	0.118	0.138	0.158		
	Ву	0.060	0.080	0.100		
	Wx	0.290	0.310	0.330		
	Wy	0.309	0.329	0.349		
	ΘI	-	80	-		
*1) Viewing Angle	⊝r	-	80	-	Dogwoo	C/R>10
-7 viewing Angle	⊝u	-	80	-	Degree	Fig.4
	⊖d	-	80	-		

#### Notes:

1. Contrast Ratio (CR) is defined mathematically as:

Contrast Ratio = Surface Luminance with all white pixels
Surface Luminance with all black pixels

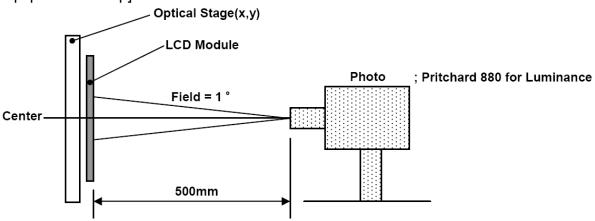
- 2. Surface luminance is the center point across the TFT-LCD surface 500mm from the surface with all pixels displaying white. For more information see FIG 1.
- 3. Response time is the time required for the display to transition from white to black (Rise Time, Tr) and from black to white (Falling Time, Tf). For additional information see FIG 3.
- 4. Viewing angle is the angle at which the contrast ratio is greater than 10. The angles are determined for the horizontal or x axis and the vertical or y axis with respect to the z axis which is normal to the TFT-LCD surface. For more information see FIG 5.
- 5. Optimum contrast is obtained by adjusting the TFT-LCD threshold voltage (Vth & Vsat).

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### FIG. 1 Optical Characteristic Measurement Equipment and Method

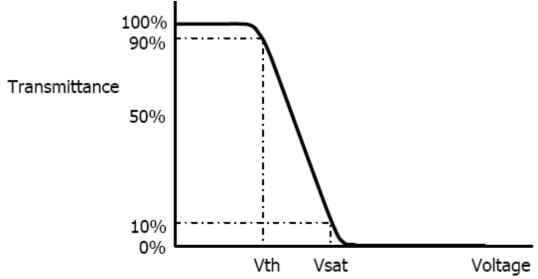
[Test Equipment Set Up]



Measuring Condition;

- -Measuring surroundings: Darkroom
- -Measuring temperature: Ta=25°C
- -Adjust operating voltage to get optimum contrast at the center of the display.
- -Measured value at the center point of LCD panel after more than 30 minutes while backlight turning on.

FIG. 2 The definition of Vth and Vsat

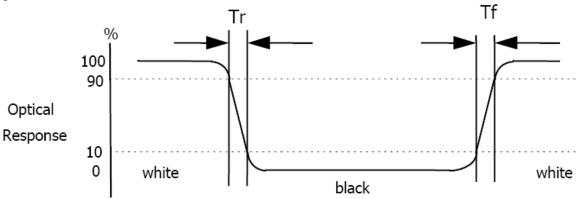


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#### FIG. 3 The definition of Response Time

The response time is defined as the following figure and shall be measured by switching the input signal for "black" and "white".



\* Voltage conditions for Response time

Vgate: 20V DC Vdata: 0V~5V DC Vcom: 0V (Ground)

FIG. 4 The definition of viewing angle: <dimension of viewing angle range>

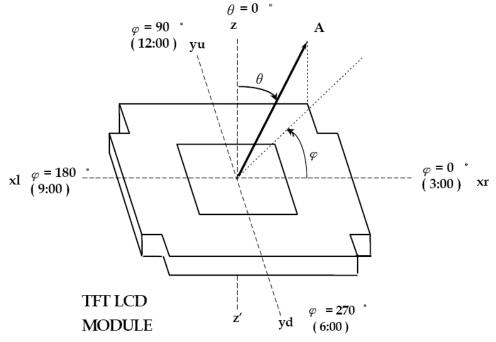
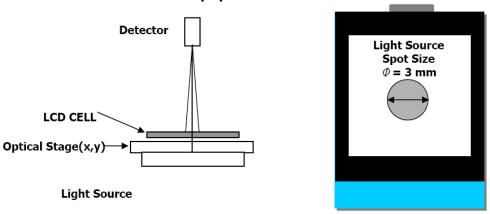


FIG. 5 Response Time Measurement Equipment and Method





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11. Reliability Test Conditions and Methods

NO.	TEST ITEMS	TEST CONDITION	INSPECTION AFTER TEST
	High Temperature Storage	80°C±2°C×200Hours	
	Low Temperature Storage	-30°C±2°C×200Hours	
	High Temperature Operating	70°C±2°C×120Hours	Inspection after 2~4hours storage at room temperature,
	Low Temperature Operating	-20°C±2°C×120Hours	the samples should be free from defects: 1, Air bubble in the
	Temperature Cycle(Storage)	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$	LCD. 2, Seal leak. 3, Non-display. 4, Missing segments. 5, Glass crack.
	Damp Proof Test (Storage)	50°C±5°C×90%RH×120Hours	6, Current IDD is twice higher than initial value.
	Vibration Test	Frequency:10Hz~55Hz~10Hz Amplitude:1.5M X,Y,Z direction for total 3hours (Packing Condition)	7, The surface shall be free from damage. 8, The electric characteristic requirements shall be
	Drooping Test	Drop to the ground from 1M height one time every side of carton. (Packing Condition)	satisfied.
	ESD Test	Voltage:±8KV,R:330Ω,C:150PF,Air Mode,10times	

#### **REMARK:**

- 1, The Test samples should be applied to only one test item.
- 2, Sample side for each test item is 5~10pcs.
- 3,For Damp Proof Test, Pure water(Resistance  $> 10M\Omega$ )should be used.
- 4,In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judge as a good part.
- 5, EL evaluation should be accepted from reliability test with humidity and temperature: Some defects such as black spot/blemish can happen by natural chemical reaction with humidity and Fluorescence EL has.
- 6, Failure Judgment Criterion: Basic Specification Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.



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## 12. Inspection Standard

This standard apply to C-STN/TFT module

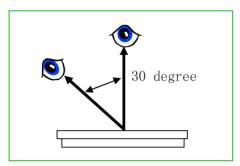
#### 1. Spot check plan:

According to spot check level  ${
m II}$ ,MIL-STD-105D Level  ${
m II}$ ,the rank of accept or reject is below:

3A、2A: major non-conformance: AQL 0.25 minor non-conformance: AQL 0.4

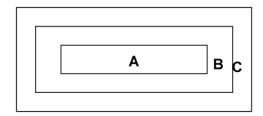
1A: major non-conformance: AQL 0.65 minor non-conformance: AQL 1.

#### 2. Inspection condition:



Under daylight lamp 20 $\sim$ 40W, product distance inspector 'eye 30cm,incline degree 30°.

#### 3. LCD area define:



Area A: display area

Area B: VA area

Area C: out of VA area, not in sight after assembly

Remark: non-conformance at area C, but is OK that isn't influence reliability of product & assembly by customer.



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## 4. Inspection standard

## 4.1 Major non-conformance

NO.	Item	Inspection standard	Rate
4.1.1	Function non-conformance	<ol> <li>No display, display abnormally</li> <li>Miss line, short</li> <li>B/L no function or function abnormally</li> <li>TP no function</li> </ol>	major
4.1.2	miss	No matter miss what component	
4.1.3	Out of size	Module dimension out of spec	

## 4.2 Appearance non-conformance

NO.	Item		Inspection standard						
		$\Phi = \frac{+3}{2}$			fine Φ		X.	Ţ À	
		A grade			Mostor		n'41	$\neg$	
	Black or	size (mm	rea	A	Most ap	B	C		
4.2.1	white spot (power	Ф≤0.1	0		ignore				Minor
	on)	0.10<Φ≤	0.15		4				
		0.15<Φ≤	0.20		2		ignore		
		0.20<Φ≤	0.25		1				
		0.25<	Φ	0					
		Most approv	ve 4 da	mages	s, dot to	dot ≥	≥10mm		
		A grade Size(mm) Most approve q'ty							1
		L(length)	<u> </u>	ridth)	Α		В	C	
		ignore	W≤	0.03		ignore	,		
4.2.2 wh	Black or white line (power	L≤5.0		3< 0.05	3				Minor
	on)	L≤3.0	0.05< W≤0.07		2			ignore	
			0.07	′ <w< td=""><td></td><td>at with</td><td>dot nance</td><td></td><td></td></w<>		at with	dot nance		
		Most approv	ve 3 da	mages	s, line to	line	≥10mm		



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4.2.3	Polarizer position	Polarizer attach     Polarizer must unless)		allow out of LCD. area (special require	Minor
4.2.4	LCD non-conform ance	(i) crash at side (range)  X  ≤3.0  Crash dis  (ii) commonly surf  X  ≤2.0  (iii) crack  Disallow extend	Y   S  Sallow extend to IT  Face scathe  Y	Z ignore	Minor
4.2.5	Contrast voltage warp	VOP/VIcd voltage o	Minor		
4.2.6	color	Color & luminance	of module scope r	eference spec	Minor
4.2.7	Cross talk	Reference confirme	ed limit sample		Minor



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### 13. Handling Precautions

### 13.1 Mounting method

The LCD panel of AMSON TFT module consists of two thin glass plates with polarizes which easily be damaged. And since the module in so constructed as to be fixed by utilizing fitting holes in the printed circuit board.

Extreme care should be needed when handling the LCD modules.

### 13.2 Caution of LCD handling and cleaning

When cleaning the display surface, Use soft cloth with solvent

[Recommended below] and wipe lightly

- Isopropyl alcohol
- Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns Do not use the following solvent on the pad or prevent it from being contaminated:

- Soldering flux
- Chlorine (CI), Sulfur (S)

If goods were sent without being sili8con coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happen by miss-handling or using some materials such as Chlorine (CI), Sulfur (S) from customer, Responsibility is on customer.

### 13.3 Caution against static charge

The LCD module use C-MOS LSI drivers, so we recommended that you:

Connect any unused input terminal to VDD or GND, do not input any signals before power is turned on, and ground your body, work/assembly areas, and assembly equipment to protect against static electricity.

### 13.4 packing

- Module employs LCD elements and must be treated as such.
- Avoid intense shock and falls from a height.
- To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity

### 13.5 Caution for operation

- It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life.
- An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.
- Response time will be extremely delayed at lower temperature then the operating temperature range and on the other hand at higher temperature LCD's how dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operation temperature.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- Slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.
  - Usage under the maximum operating temperature, 50%Rh or less is required.



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### 13.6 storing

In the case of storing for a long period of time for instance, for years for the purpose or replacement use, the following ways are recommended.

- Storage in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it. And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature range.
- Storing with no touch on polarizer surface by the anything else.
   [It is recommended to store them as they have been contained in the inner container at the time of delivery from us.

### 13.7 Safety

- It is recommendable to crash damaged or unnecessary LCD's into pieces and wash off liquid crystal by either of solvents such as acetone and ethanol, which should be burned up later.
- When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

#### 14. Precaution for Use

#### 14.1

A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

#### 14.2

On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

- When a question is arisen in this specification.
- When a new problem is arisen this is not specified in this specification.
- When an inspection specifications change or operating condition change in customer is reported to AMSON TFT and some problem is arisen in this specification due to the change.
- When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

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## 15. Packing Method

